

Raise3D DF2 Technical Specifications

The Raise3D DF2 solution is a Digital Light Printing (DLP) system offering speed, quality, exceptional reliability and efficient workflow via RFID. It is designed for engineering prototyping, manufacturing aids, and low-volume production using a wide variety of high-performance

Printer	Raise3D DF2	
Printer Hardware	Print Technology Build Volume (W × D × H) XY Pixel Size XY Resolution Max Z Workload Layer Height Max Printing Speed Resin Level Detection Auto Resin Refill Control Panel Level Calibration Chamber Heating	DLP 200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch) 78.5 micron 2560 × 1440 12 kg 50-100 micron 25 mm/h (0.1 mm per layer) Yes Yes Touch Screen (1920 × 720, Magic Layout) Calibrated in Factory Yes (Max 40°C)
Resins (Available Options)	Raise3D Standard Raise3D High Detail Raise3D Tough 2K Raise3D Rigid 3K Raise3D High Clear Raise3D High Temperature Open Resin Program	White Apricot Grey Grey Coming Soon Coming Soon Coming Soon
Software and Network	Connectivity Network Slicing Software Remote Management Software Supported File Types Supported OS	Wi-Fi, LAN, USB port × 2, Live camera Ethernet, Wireless 802.11 b/g/n ideaMaker RaiseCloud STL/ OBJ/ 3MF/ OLTP WINDOWS/ macOS/ LINUX
Operation and Shipping	Power Supply Input Operating Ambient Temperature Storage Temperature Machine Size (W × D × H) Weight Shipping Dimensions	100-240VAC, 50/60 Hz 230V @ 3.3A 15 - 30°C, 10 - 90% RH Non-Condensing (HOLD) -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) 450 × 400 × 730 mm (17.7 × 15.7 × 28.7 inch) 40 kg (Net Weight) 59.4 kg (Gross Weight) 710 × 595 × 980 mm (28.0 × 23.4 × 38.6 inch)